

## FSC-BT821

### 4.2 Dual Mode Bluetooth Module Data Sheet

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## Release Record

Version Number	Release Date	Comments
Revision 1.0	2014-11-5	First Release
Revision 1.0	2015-05-22	
Revision 1.1	2015-09-06	
Revision 1.2	2015-10-21	Modify the pin definition
Revision 1.3	2015-12-14	Increase the application circuit diagram
Revision 1.4	2017-04-12	Dealing with part of the customers' needs, increase the single mode and dual mode recognition shipment information, increase the packaging information.
Revision 1.5	2018-05-05	Modify Bluetooth Version: Upgrade from BT4.0 to BT4.2
Revision 1.6	2020-04-30	Increase power consumption parameters
Revision 1.61	2020-10-23	Change size error

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## 1. INTRODUCTION

FSC-BT821 is a fully integrated Bluetooth module that complies with Bluetooth 4.2 dual mode protocols(BR/EDR/BLE). It supports SPP, BLE, ANCS, iBeacon profiles. It integrates Baseband controller in a small package(Need an external RF antenna), so the designers can have better flexibilities for the product shapes.

FSC-BT816 can be communicated by UART port. With Feasycom's Bluetooth stack, Customers can easily transplant to their software. Please refer to Feasycom stack design guide.

### 1.1 Block Diagram

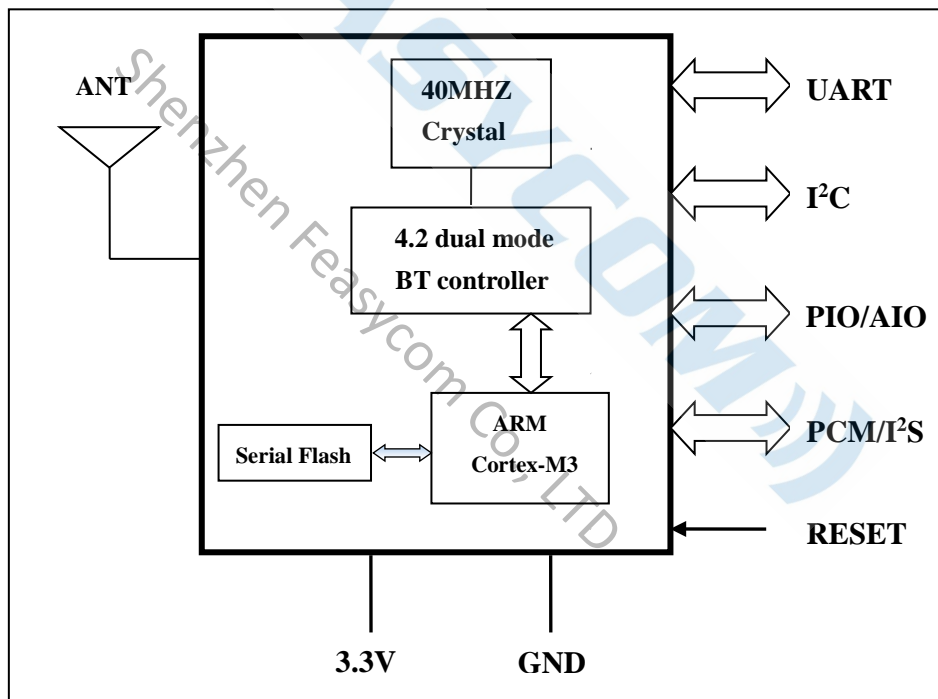


Figure 1

## 1.2 Feature

- ◆ Fully qualified Bluetooth 4.2/3.0/2.1/2.0/1.2/1.1
- ◆ Postage stamp sized form factor,
- ◆ Low power
- ◆ Class 1.5 support(high output power)
- ◆ The default UART Baud rate is 115.2Kbps and can support from 1200bps up to 921Kbps,.
- ◆ UART, I<sup>2</sup>C,PCM / I<sup>2</sup>S data connection interfaces.
- ◆ Support the OTA upgrade.
- ◆ Bluetooth stack profiles support: SPP, HID, HFP/HSP, A2DP, AVRCP, MAP, and all BLE protocols.
- ◆ Power Consumption In Working Mode (VDD\_3V3 at 3.3 V)
  - Discoverable: 18.5mA
  - BR/EDR Connection: 22.4mA
  - LE Connection: 17.9mA
  - BR/EDR Connection @ 115200bps: 23.4mA

## 1.3 Application

- ◆ Smart Watch and Bluetooth Bracelet
- ◆ Health & Medical devices
- ◆ Wireless POS
- ◆ Measurement and monitoring systems
- ◆ Industrial sensors and controls
- ◆ Asset tracking

## 2. GENERAL SPECIFICATION

General Specification	
Chipset	Realtek
Product	FSC-BT821
Dimension	12mm x 15mm x 1.8mm
Bluetooth Specification	Bluetooth V4.2 (Dual Mode)
Power Supply	3.3 Volt DC
Output Power	5.5 dBm (Class 1.5)
Sensitivity	-82dBm@0.1%BER
Frequency Band	2.402GHz -2.480GHz ISM band
Modulation	GFSK, /4-DQPSK, 8DPSK
Baseband Crystal OSC	40MHz
Hopping & channels	1600hops/sec, 1MHz channel space,79 Channels(BT 4.2 to 2MHz channel space)
RF Input Impedance	50 ohms
Antenna	External
Interface	Data: UART, I <sup>2</sup> C, PCM / I <sup>2</sup> S
Profile	SPP, GATT(BLE Standard) MFI,Airsync,ANCS, iBeacon, MAP(optional),OTA(optional)
Temperature	0°C to +70 °C
Humidity	10%~95% Non-Condensing
Environmental	RoHS Compliant

Table 1

**3. PHYSICAL CHARACTERISTIC**

FSC-BT821 Dimension: 15mm(L) x 12mm(W) x 1.8mm(H).

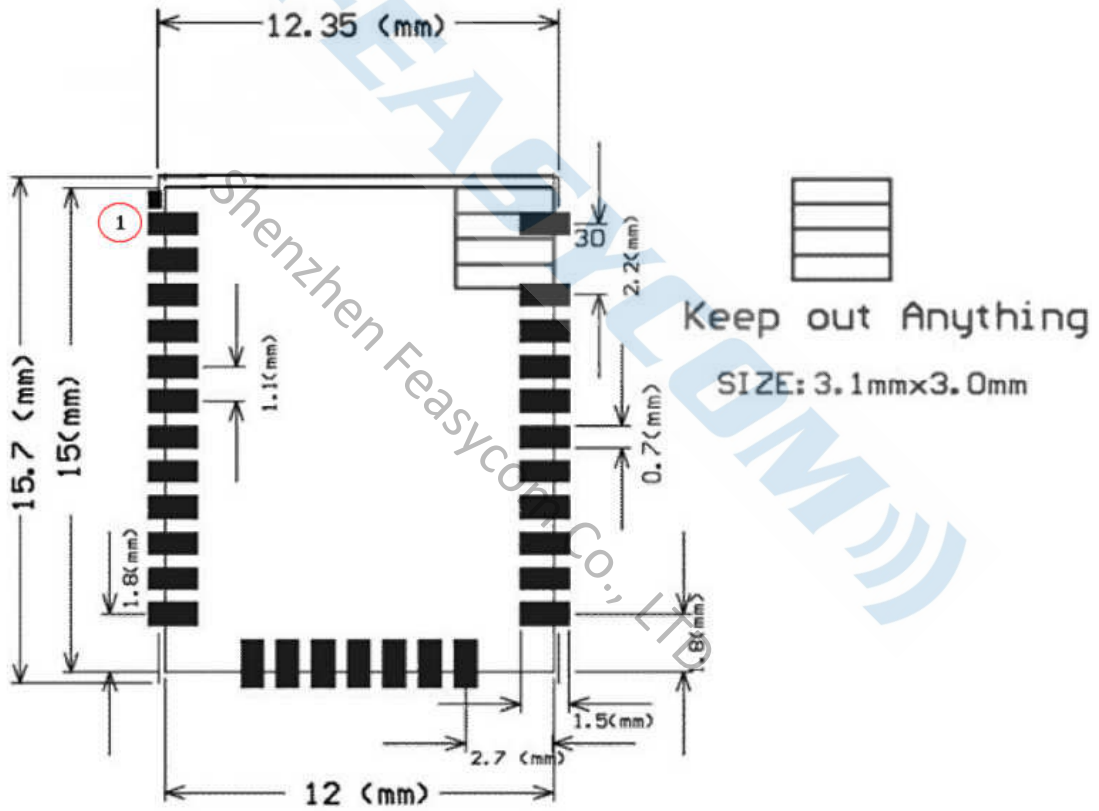
Tolerance: +/-0.25mm

Module size: 15mm x 12mm

Screen outline: 15.7mm x 12.35mm

Pad size: 1.5mm x 0.7mm

Pad pitch: 1.1mm



**Figure 2:** Package Dimensions (TOP VIEW)

## 4. PIN DEFINITION DESCRIPTIONS

\* **Special tips:** PA4, PA5, PA6, PA7 I/O port for reuse.

When using the OTA function upgrade (air), please send the I/O mouth dangling;  
 If the I/O port to connect the MCU,  
 then set the MCU I/O ports for the input port or high impedance state.

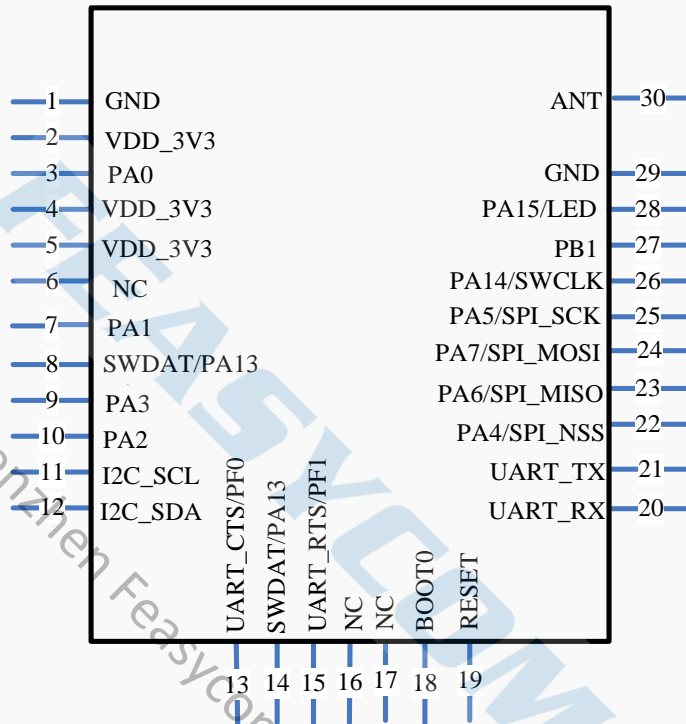


Figure 3: FSC-BT821 PIN Diagram

Pin	Pin Name	Pad Type	Description
1	GND	VSS	Power Ground
2	VDD_3V3	VDD	Power supply voltage 3.3V
3	PA0	I/O	Programmable input/output line
4	VDD_3V3	VDD	Power supply voltage 3.3V
5	VDD_3V3	VDD	Power supply voltage 3.3V
6	NC	NC	NC
7	PA1	I/O	Programmable input/output line
8	PA13 or SWDAT	I/O	Programmable input/output line Or Update Interface(SWDAT)

9	PA3	I/O	Programmable input/output line
10	PA2	I/O	Programmable input/output line
11	I <sup>2</sup> C_SCL	Bi-directional	The I <sup>2</sup> C clk line
12	I <sup>2</sup> C_SDA	Bi-directional	The I <sup>2</sup> C data line
13	PF0 or UART CTS	CMOS Input	Programmable input/output line Or UART Clear To Send Active Low
14	PA13 or SWDAT	I/O	Programmable input/output line Or Update Interface(SWDAT)
15	PF1 or UART RTS	CMOS Output	Programmable input/output line Or UART Request To Send Active Low
16	NC	NC	NC
17	NC	NC	NC
18	BOOT0	Bi-directional	The default is low. (internal 10K resistance drop) When writing to MCU when using the serial port, this pin is connected with the high level.
19	RESET	CMOS input	Reset if low. Input debounced so must be low for >5ms to cause a reset.
20	UART-RX	CMOS input	UART data input
21	UART-TX	CMOS output	UART data output
22	PA4/SPI_NSS	I/O	Programmable input/output line * The I/O port for reuse.
23	PA6/SPI_MISO	I/O	Programmable input/output line * The I/O port for reuse.
24	PA7/SPI_MOSI	I/O	Programmable input/output line * The I/O port for reuse.
25	PA5/SPI_SCK	I/O	Programmable input/output line * The I/O port for reuse.
26	PA14 or SWCLK	I/O	Programmable input/output line Or Update Interface(SWCLK)
27	PB1	I/O	Programmable input/output line
28	PA15	I/O	Programmable input/output line
29	GND	VSS	Power Ground
30	ANT	RF_IN	Bluetooth 50ohm transmitter output/ receiver input

Table 2



## 5. Interface Characteristics

### 5.1 UART Interface

Four signals are used to implement the UART function. When FSC-BT821 is connected to another digital device, UART\_RX and UART\_TX transfer data between the two devices. The remaining two signals, UART\_CTS and UART\_RTS, can be used to implement RS232 hardware flow control where both are active low indicators.

The interface consists of four-line connection as described in below:

Signal name	Driving source	Description
UART-TX	FSC-BT821 module	Data from FSC-BT821 module
UART-RX	Host	Data from Host
UART-RTS	FSC-BT821 module	Request to send output of FSC-BT821 module
UART-CTS	Host	Clear to send input of FSC-BT821 module

**Table 3**

Default Data Format

Property	Possible Values
BCSP-Specific Hardware	Enable
Baud Rate	115.2 Kbps
Flow Control	None
Data bit length	8bit
Parity	None
Number of Stop Bits	1

**Table 4**

### 5.2 I<sup>2</sup>C Interface

- ◆ Up to two I2C bus interfaces can support both master and slave mode with a frequency up to 400KHZ.
- ◆ Provide arbitration function, optional PEC(packet error checking) generation and checking.
- ◆ Supports 7-bit and 10-bit addressing mode and general call addressing mode.

The I2C interface is an internal circuit allowing communication with an external I2C interface which is an industry standard two line serial interface used for connection to external hardware. These two serial lines are known as a serial data line (SDA) and a serial clock line (SCL). The I2C module provides two data transfer rates: 100 kHz of standard mode or 400kHz of the fast mode. The I2C module also has an arbitration detect function to prevent the situation where more than one master attempts to transmit data to the I2C bus at the same time. A CRC-8 calculator is also provided in I2C interface to perform packet error checking for I2C data.

### 5.3 Analog to digital converter (ADC)

- ◆ 12-bit SAR ADC engine with up to 1 MSPS conversion rate
- ◆ Conversion range:  $V_{VSSA}$  to  $V_{DDA}$  (2.6 to 3.6 V)
- ◆ Temperature sensor

One 12-bit 1  $\mu$ s multi-channel ADC is integrated in the device.

The conversion range is between  $2.6\text{ V} < V_{DDA} < 3.6\text{ V}$ . An analog watchdog block can be used to detect the channels, which are required to remain within a specific threshold window. A configurable channel management block of analog inputs also can be used to perform conversions in single, continuous, scan or discontinuous mode to support more advanced usages. The ADC can be triggered from the events generated by the general-purpose timers (TMx) and the advanced-control timers (TM1) with internal connection.

The temperature sensor can be used to generate a voltage that varies linearly with temperature. Each device is factory-calibrated to improve the accuracy and the calibration data are stored in the system memory area.

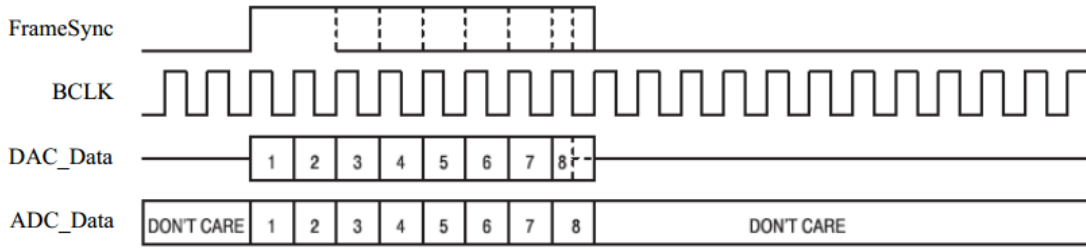
### 5.4 PCM Interface Characteristics

The FSC-BT821 supports a PCM digital audio interface that is used for transmitting digital audio/voice data to/from the Audio Codec. Features are supported as below

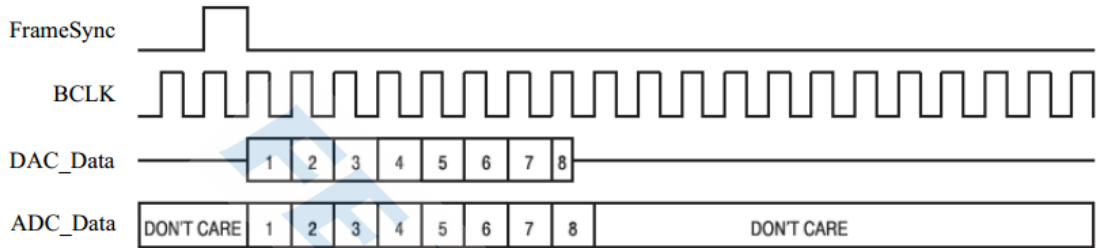
- ◆ Supports Master and Slave mode
- ◆ Programmable long/short Frame Sync
- ◆ Supports 8-bit A-law/ $\mu$ -law, and 13/16-bit linear PCM formats
- ◆ Supports sign-extension and zero-padding for 8-bit and 13-bit samples
- ◆ Supports padding of Audio Gain to 13-bit samples
- ◆ PCM Master Clock Output: 64, 128, 256, or 512kHz
- ◆ Supports SCO/ESCO link

#### 5.4.1 PCM Format

FrameSync is the synchronizing function used to control the transfer of DAC\_Data and ADC\_Data. A Long FrameSync indicates the start of ADC\_Data at the rising edge of FrameSync (Figure 3), and a Short FrameSync indicates the start of ADC\_Data at the falling edge of FrameSync (Figure 4).



**Figure 4:** Long FrameSync



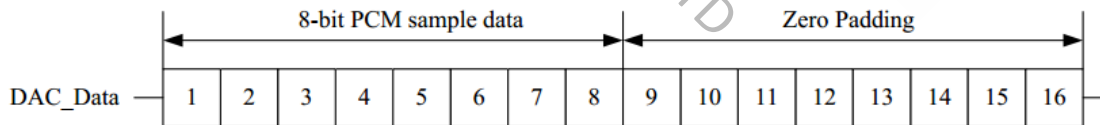
**Figure 5:** Short FrameSync

### 5.4.2 Sign Extension and Zero Padding for 8-Bit and 13-Bit Samples

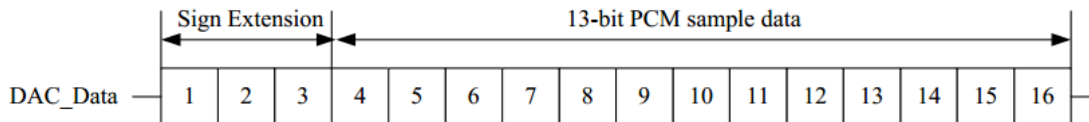
For 16-bit linear PCM output, 3 or 8 unused bits may be sign extended/zero padded.



**Figure 6:** 16-Bit Output Data with 8-Bit PCM Sample Data and Sign Extension

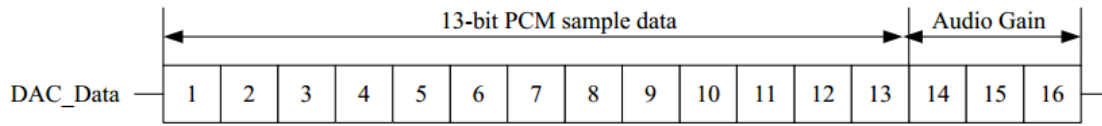


**Figure 7:** 16-Bit Output Data with 8-Bit PCM Sample Data and Zero Padding



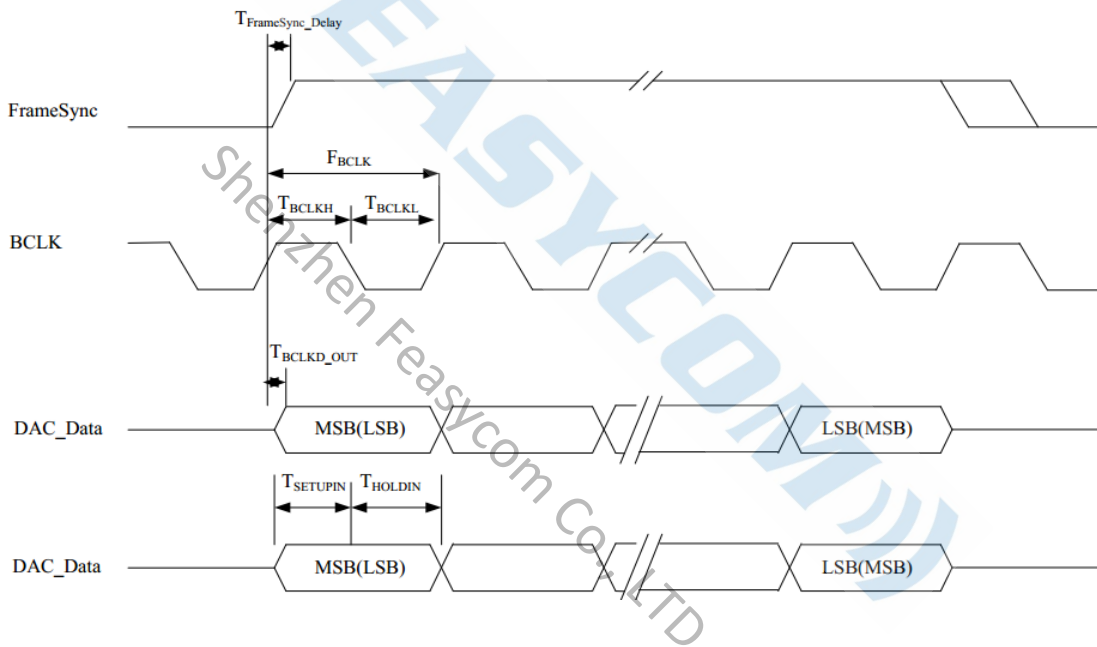
**Figure 8:** 16-Bit Output Data with 13-Bit PCM Sample Data and Sign Extension

For 16-bit linear PCM output, 3-bit programmable audio gain value can be padded to 13-bit sample data.

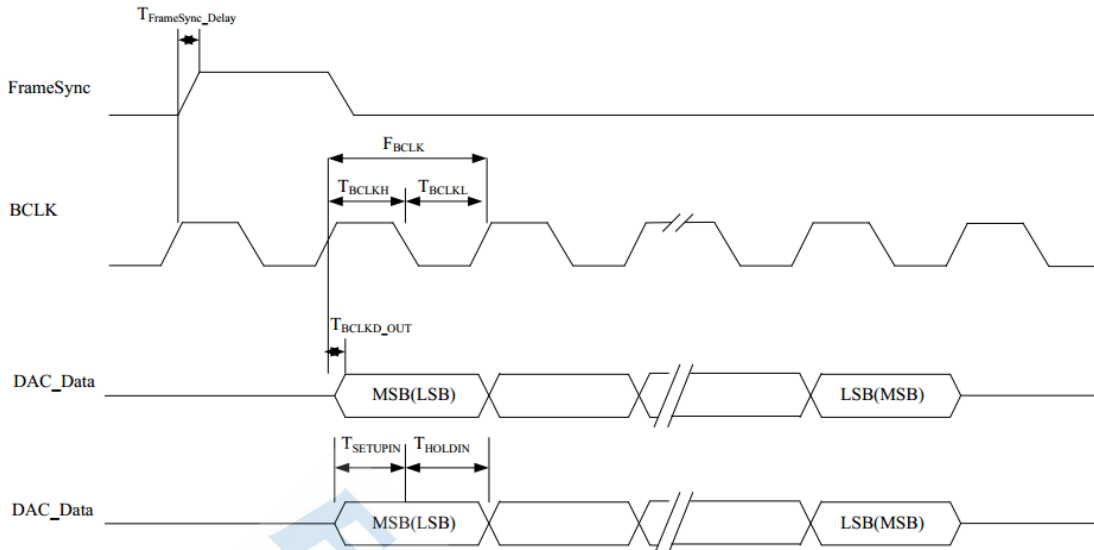


**Figure 9:** 16-Bit Output Data with 13-Bit PCM Sample Data and Audio Gain

5.4.3 PCM Interface Timing



**Figure 10:** PCM Interface (Long FrameSync)



**Figure 11:** PCM Interface (Short FrameSync)

Symbol	Description	Min.	Typ.	Max.	Unit
$F_{BCLK}$	Frequency of BCLK (Master)	64	-	512	kHz
$F_{FrameSync}$	Frequency of Frame Sync (Master)	-	8	-	kHz
$F_{BCLK}$	Frequency of BCLK (Slave)	64	-	512	kHz
$F_{FrameSync}$	Frequency of Frame Sync (Slave)	-	8	-	kHz
D	Data Size	8	8	16	bits
N	Number of Slots Per Frame	1	1	1	Slots

**Table 5:** PCM Interface Clock Specifications

Symbol	Description	Min.	Typ.	Max.	Unit
$T_{BCLKH}$	High Period of BCLK	980	-	-	ns
$T_{BCLKL}$	Low Period of BCLK	970	-	-	ns
$T_{FrameSync\_Delay}$	Delay Time from BCLK High to Frame Sync High	-	-	75	ns
$T_{BCLKD\_OUT}$	Delay Time from BCLK High to Valid DAC_Data	-	-	125	ns
$T_{SETUPIN}$	Set-up Time for ADC_Data Valid to BCLK Low	10	-	-	ns
$T_{HOLDIN}$	Hold Time for BCLK Low to ADC_Data Invalid	125	-	-	ns

**Table 6:** PCM Interface Timing

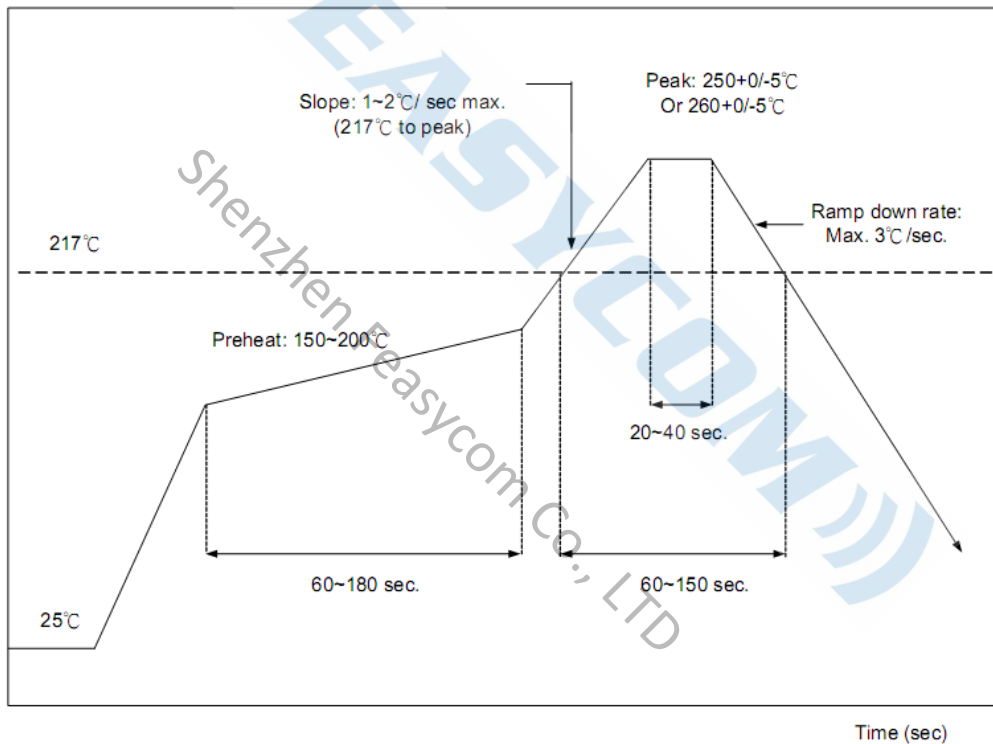
### 5.4.4 PCM Interface Signal Levels

The PCM signal level ranges from 1.8V to 3.3V.

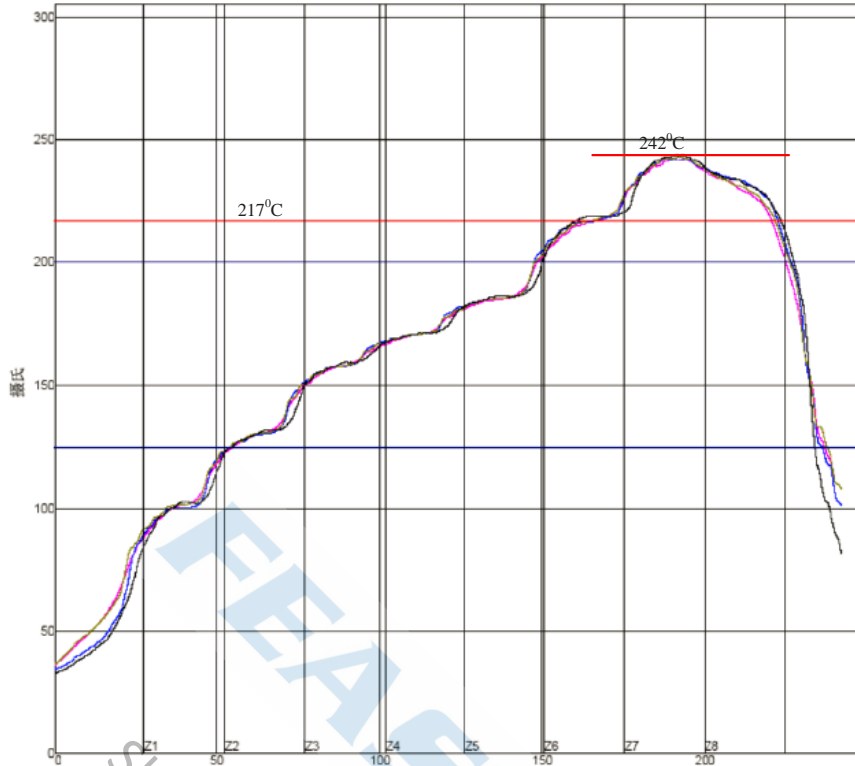
## 6. RECOMMENDED TEMPERATURE REFLOW PROFILE

The re-flow profiles are illustrated in Figure 11 and Figure 12 below.

- Follow: IPC/JEDEC J-STD-020 C
- Condition:
  - Average ramp-up rate(217°C to peak):1~2°C/sec max.
  - Preheat:150~200C,60~180 seconds
  - Temperature maintained above 217°C:60~150 seconds
  - Time within 5°C of actual peak temperature:20~40 sec.
  - Peak temperature:250+0/-5°C or 260+0/-5°C
  - Ramp-down rate:3°C/sec.max.
  - Time 25°C to peak temperature:8 minutes max
  - Cycle interval: 5 minus



**Figure 12:** Typical Lead-free Re-flow Solder Profile



**Figure 1:** Typical Lead-free Re-flow

The soldering profile depends on various parameters according to the use of different solder and material. The data here is given only for guidance on solder re-flow.

FSC-BT821 will withstand up to two re-flows to a maximum temperature of 245°C.

## 7. Reliability and Environmental Specification

### 7.1 Temperature test

Put the module in demo board which uses exit power supply, power on the module and connect to mobile. Then put the demo in the -20°C space for 1 hour and then move to +70°C space within 1minute, after 1 hour move back to -20°C space within1 minute. This is 1 cycle. The cycles are 32 times and the units have to pass the testing.

### 7.2 Vibration Test

The module is being tested without package. The displacement requests 1.5mm and sample is vibrated in three directions(X,Y,Z).Vibration frequency set as 0.5G , a sweep rate of 0.1 octave/min from 5Hz to 100Hz last for 90 minutes each direction. Vibration frequency set as 1.5G, a sweep rate of 0.25 octave/min from 100Hz to 500Hz last for 20 minutes each direction.

### 7.3 Desquamation test

Use clamp to fix the module, measure the pull of the component in the module, make sure the module`s soldering is good.

## 7.4 Drop test

Free fall the module (condition built in a wrapper which can defend ESD) from 150cm height to cement ground, each side twice, total twelve times. The appearance will not be damaged and all functions OK.

## 7.5 Packaging information

After unpacking, the module should be stored in environment as follows:

- Temperature:  $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$
- Humidity: <60%
- No acidity, sulfur or chlorine environment

The module must be used in four days after unpacking.

## 8. Layout and Soldering Considerations

### 8.1 Soldering Recommendations

FSC-BT821 is compatible with industrial standard reflow profile for Pb-free solders. The reflow profile used is dependent on the thermal mass of the entire populated PCB, heat transfer efficiency of the oven and particular type of solder paste used. Consult the datasheet of particular solder paste for profile configurations.

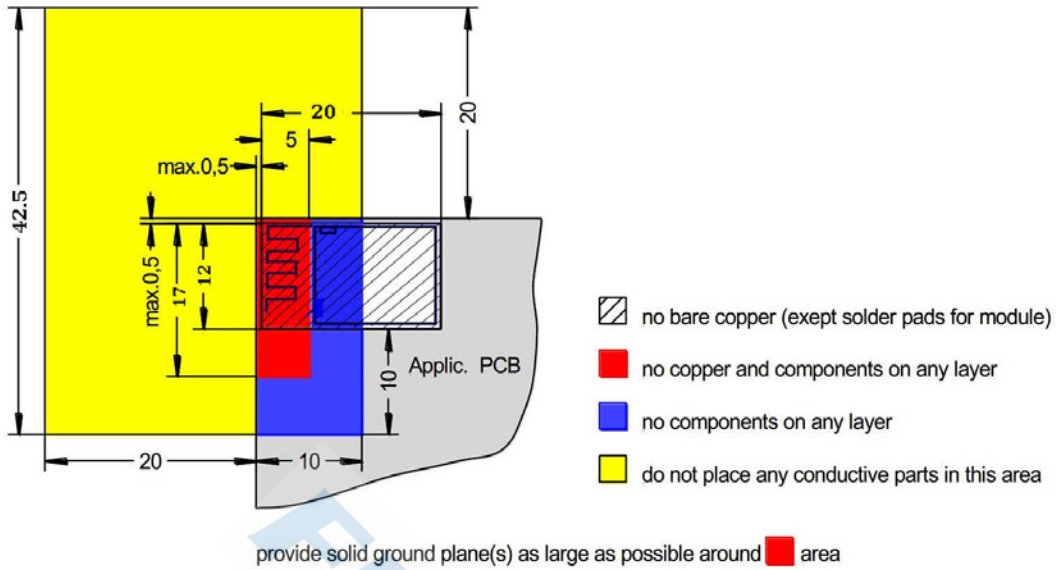
Feasycom will give following recommendations for soldering the module to ensure reliable solder joint and operation of the module after soldering. Since the profile used is process and layout dependent, the optimum profile should be studied case by case. Thus following recommendation should be taken as a starting point guide.

### 8.2 Layout Guidelines

It is strongly recommended to use good layout practices to ensure proper operation of the module. Placing copper or any metal near antenna deteriorates its operation by having effect on the matching properties. Metal shield around the antenna will prevent the radiation and thus metal case should not be used with the module. Use grounding vias separated max 3 mm apart at the edge of grounding areas to prevent RF penetrating inside the PCB and causing an unintentional resonator. Use GND vias all around the PCB edges.

The mother board should have no bare conductors or vias in this restricted area, because it is not covered by stop mask print. Also no copper (planes, traces or vias) are allowed in this area, because of mismatching the on-board antenna.





**Figure 14:** FSC-BT821 Restricted Area

Following recommendations helps to avoid EMC problems arising in the design. Note that each design is unique and the following list do not consider all basic design rules such as avoiding capacitive coupling between signal lines. Following list is aimed to avoid EMC problems caused by RF part of the module. Use good consideration to avoid problems arising from digital signals in the design.

Ensure that signal lines have return paths as short as possible. For example if a signal goes to an inner layer through a via, always use ground vias around it. Locate them tightly and symmetrically around the signal vias. Routing of any sensitive signals should be done in the inner layers of the PCB. Sensitive traces should have a ground area above and under the line. If this is not possible, make sure that the return path is short by other means (for example using a ground line next to the signal line).

## 9. Product Packaging Information

### 9.1 Packing (General packaging information)( default)

a, Tray vacuum

b, Tray Dimension: 180mm \* 195mm

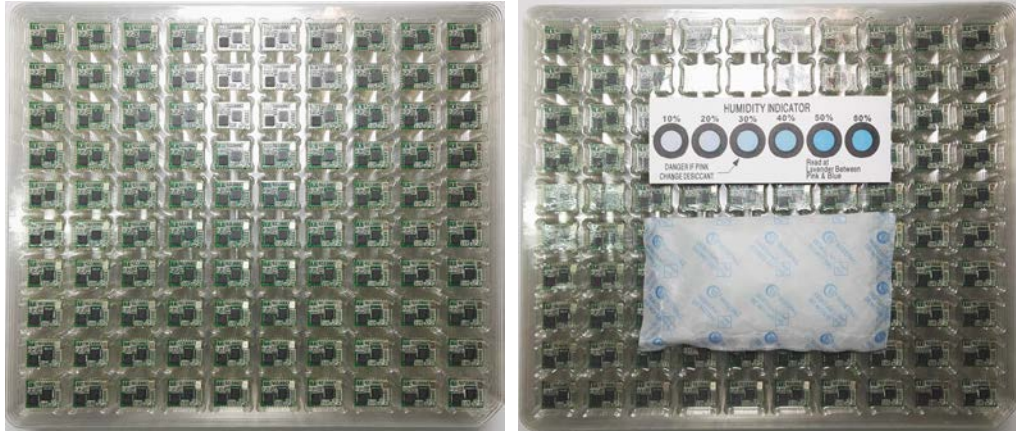


Figure 15,16,17: Product Packaging Information (Tray)

## 9.2 Packing (Customized version of the packaging information) (Optional)

### 9.2.1 Bluetooth module packaging (dual mode)



Figure 18: label(dual mode)

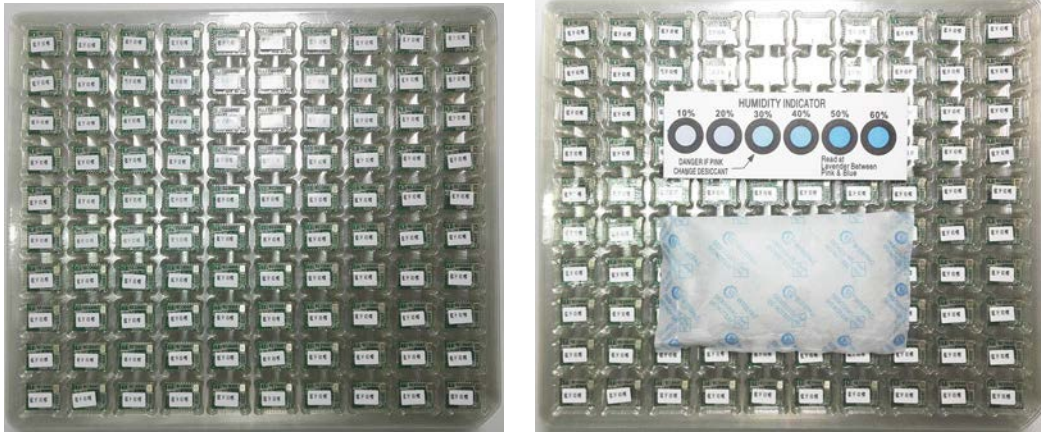


Figure 19,20,21: Product Packaging Information (Tray) (dual mode)

9.2.2 Bluetooth Single-mode 4.2 packaging

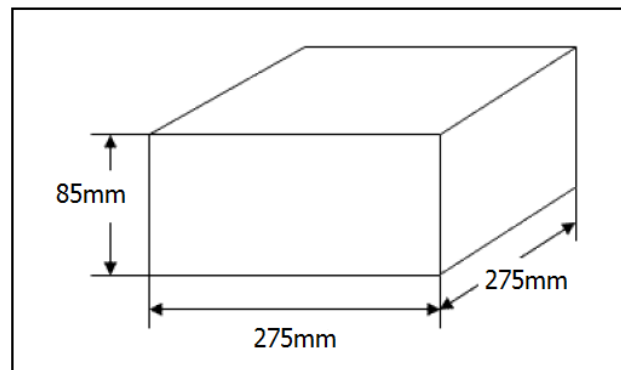


Figure 22: label (Single-mode 4.2)



Figure 23,24,25: Product Packaging Information (Tray) (Single-mode 4.2)

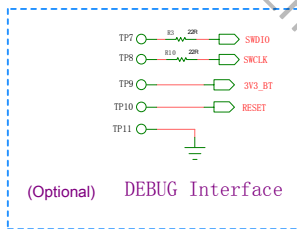
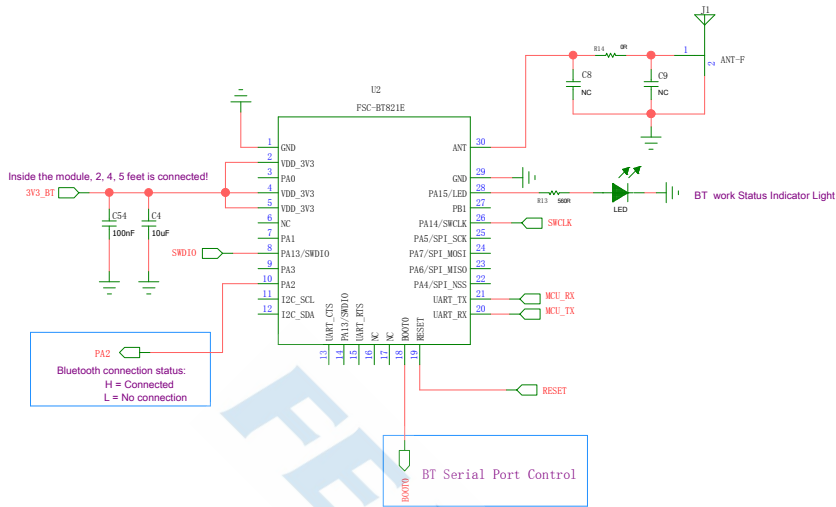
### 9.3 Packing box(Optional)



\* If require any other packing, must be confirmed with customer

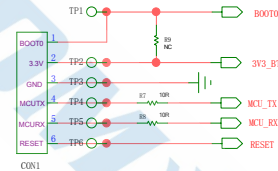
Figure 11: Packing Box

## 10.Application Schematic



	BOOT0
Serial Programming-Mode	1 (connected to the 3.3 V)
Run-Mode	Pull-down resistor already inside this module.

(Optional)



Circuit Connection Method for Using PC/CMS Port Do MCU Burning.

If need the continuous power supply upgrade mode. After finished upgrade operation, need to activate the RESET.

